

**IN THE ABSTRACT:**

Please enter the attached substitute Abstract of the Disclosure for that originally filed with this application.

**ABSTRACT OF THE DISCLOSURE**

A sink compound laminate molding process having a copper material in thickness of 0.1-0.8 mm placed at the bottom of the molding cavity with the bottom of the copper laminate fully bound to the bottom of the molding cavity, the copper being heated up to 300-600°C, and melting aluminum being filled into the molding cavity using gravity casting process to create diffusion bonding to the interface between the copper and aluminum materials, molten aluminum being cooled and cured to avail an integrated compound laminate in a given profile of heterogeneous copper and aluminum.